

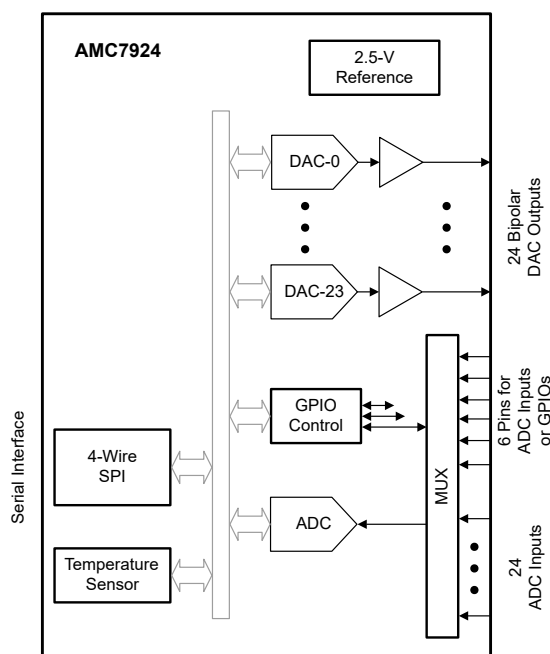
AMC7924 24-Channel, 12-Bit Analog Monitor and Controller With Multichannel ADC, Bipolar DACs, Temperature Sensor, and GPIO Ports

1 Features

- 24 monotonic 12-bit DACs
 - Programmable ranges: -10 V to 0 V , -5 V to 0 V , 0 V to 5 V , and 0 V to 10 V
 - High current drive capability
 - Autorange detector
- 24 inputs, 12-bit SAR ADC
 - High sample rate: 250 kSPS
 - Input ranges: 0 V to 5 V and 0 V to 2.5 V
 - Programmable out-of-range alarms
- 6 FlexIO pins; ADC and GPIO configurable
- Built-in sequencing features
- Internal 2.5-V reference
- Internal temperature sensor
 - Accuracy: $\pm 2.5^\circ\text{C}$, maximum
 - Resolution: 0.0625°C
- 4-wire, SPI-compatible interface
 - 1.65-V to 5.5-V operation
- Specified temperature range: -40°C to $+125^\circ\text{C}$
- Operating temperature range: -40°C to $+150^\circ\text{C}$

2 Applications

- [Active antenna system mMIMO \(AAS\)](#)
- [Macro remote radio unit \(RRU\)](#)
- [Radar](#)
- [Data acquisition \(DAQ\)](#)



Simplified Schematic

3 Description

The AMC7924 is a highly integrated analog monitor and control device designed for high-density, general-purpose monitor and control systems. The AMC7924 includes 24 12-bit digital-to-analog converters (DACs) with programmable output ranges. The device also incorporates a multiplexed, 12-bit analog-to-digital converter (ADC) with programmable threshold detectors, a temperature sensor, and an internal reference. The AMC7924 high level of integration significantly reduces component count and simplifies closed-loop system designs, thus making the device a great choice for high-density applications where board space is critical.

The device includes 24 dedicated ADC inputs and six flexible input/output (FlexIO) pins that can be configured as either additional analog inputs to the ADC or as GPIOs. Communication to the device is performed through a 4-wire, SPI-compatible interface.

The AMC7924 high-integration and wide operating temperature range make the device an excellent choice as an all-in-one bias-control circuit for the power amplifiers (PA) found in multichannel RF communication systems. The flexible DAC output ranges and built-in sequencing features allow the device to be used as a biasing controller for a large variety of transistor technologies, such as LDMOS, GaAs, and GaN. The AMC7924 feature set is similarly beneficial in general-purpose monitor and control systems.

Device Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
AMC7924	HTQFP (64)	10.00 mm × 10.00 mm

- (1) For all available packages, see the package option addendum at the end of the data sheet.



4 Device and Documentation Support

4.1 Documentation Support

4.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [AMC7924EVM user's guide](#)
- Texas Instruments, [Temperature Compensation of Power Amplifier FET Bias Voltages](#) application note

4.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

4.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

4.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

4.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

4.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
AMC7924PAPR	Active	Production	HTQFP (PAP) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AMC7924
AMC7924PAPR.A	Active	Production	HTQFP (PAP) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AMC7924
AMC7924PAPRG4	Active	Production	HTQFP (PAP) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AMC7924
AMC7924PAPRG4.A	Active	Production	HTQFP (PAP) 64	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AMC7924
AMC7924PAPT	Active	Production	HTQFP (PAP) 64	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AMC7924
AMC7924PAPT.A	Active	Production	HTQFP (PAP) 64	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	AMC7924

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AMC7924PAPR	HTQFP	PAP	64	1000	330.0	24.4	13.0	13.0	1.5	16.0	24.0	Q2
AMC7924PAPRG4	HTQFP	PAP	64	1000	330.0	24.4	13.0	13.0	1.5	16.0	24.0	Q2
AMC7924PAPT	HTQFP	PAP	64	250	330.0	24.4	13.0	13.0	1.5	16.0	24.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AMC7924PAPR	HTQFP	PAP	64	1000	367.0	367.0	55.0
AMC7924PAPRG4	HTQFP	PAP	64	1000	367.0	367.0	55.0
AMC7924PAPT	HTQFP	PAP	64	250	367.0	367.0	55.0

GENERIC PACKAGE VIEW

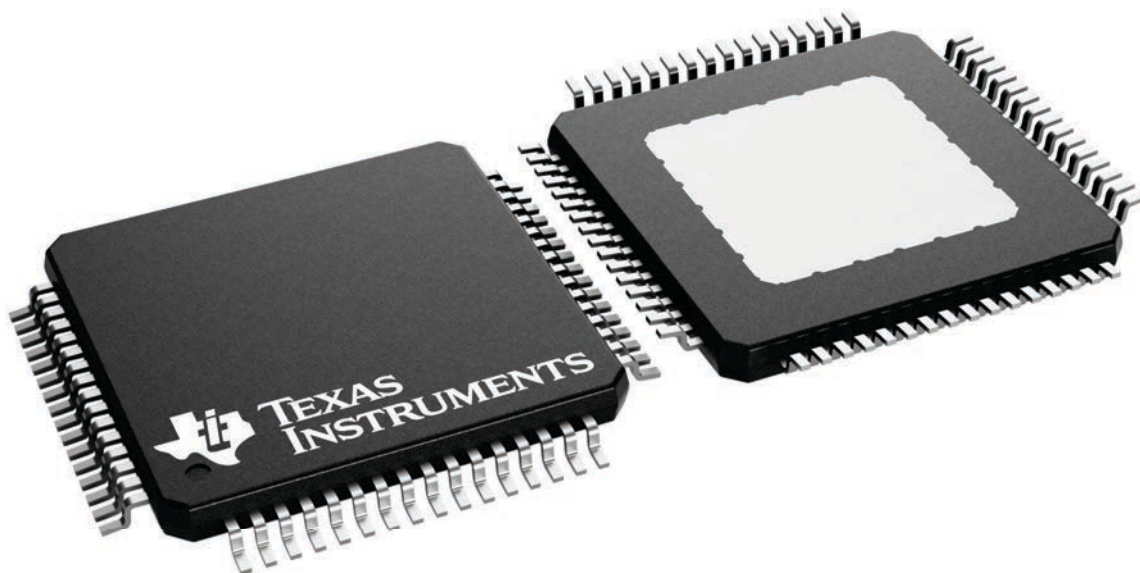
PAP 64

HTQFP - 1.2 mm max height

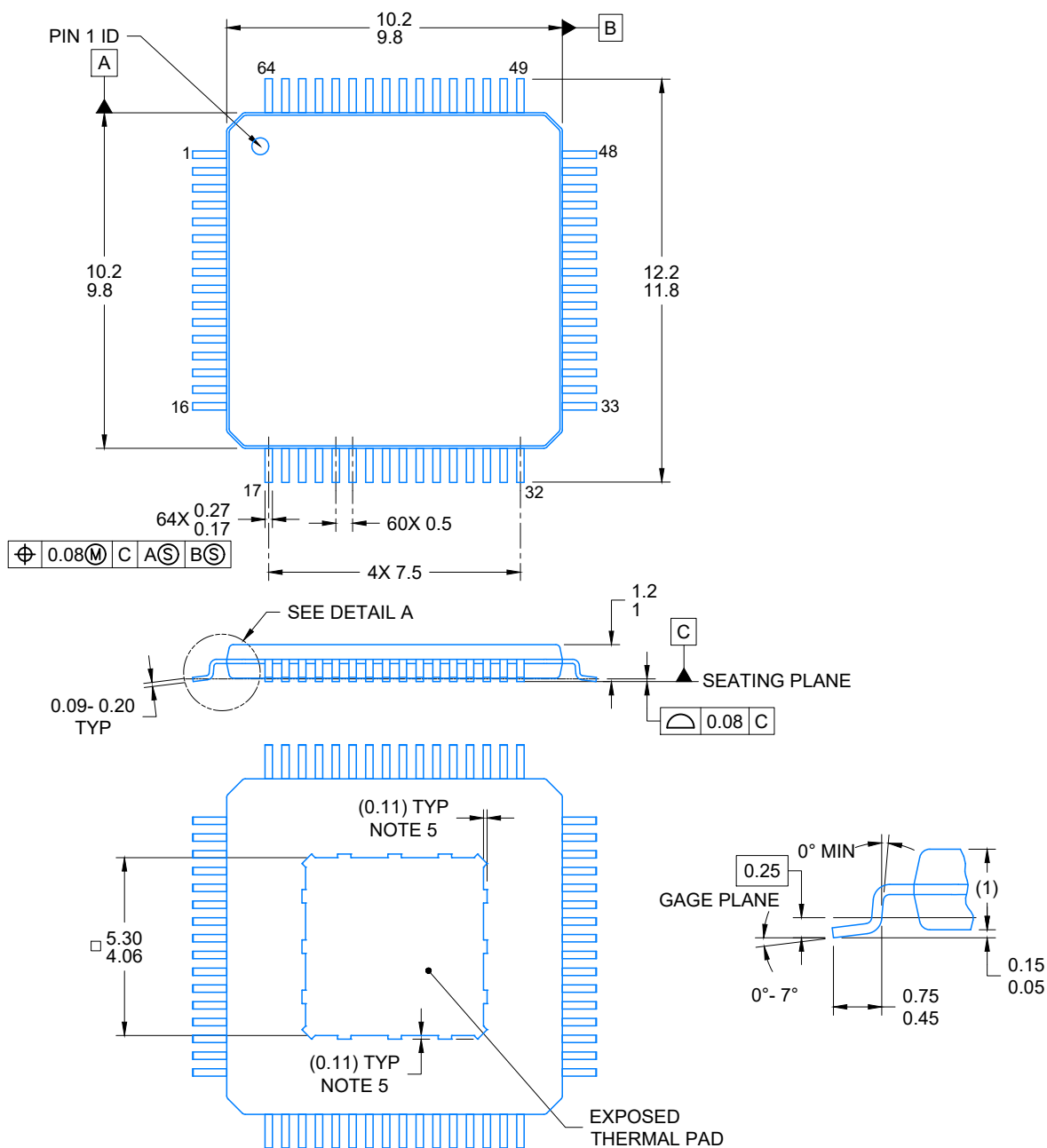
10 x 10, 0.5 mm pitch

QUAD FLATPACK

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4226442/A

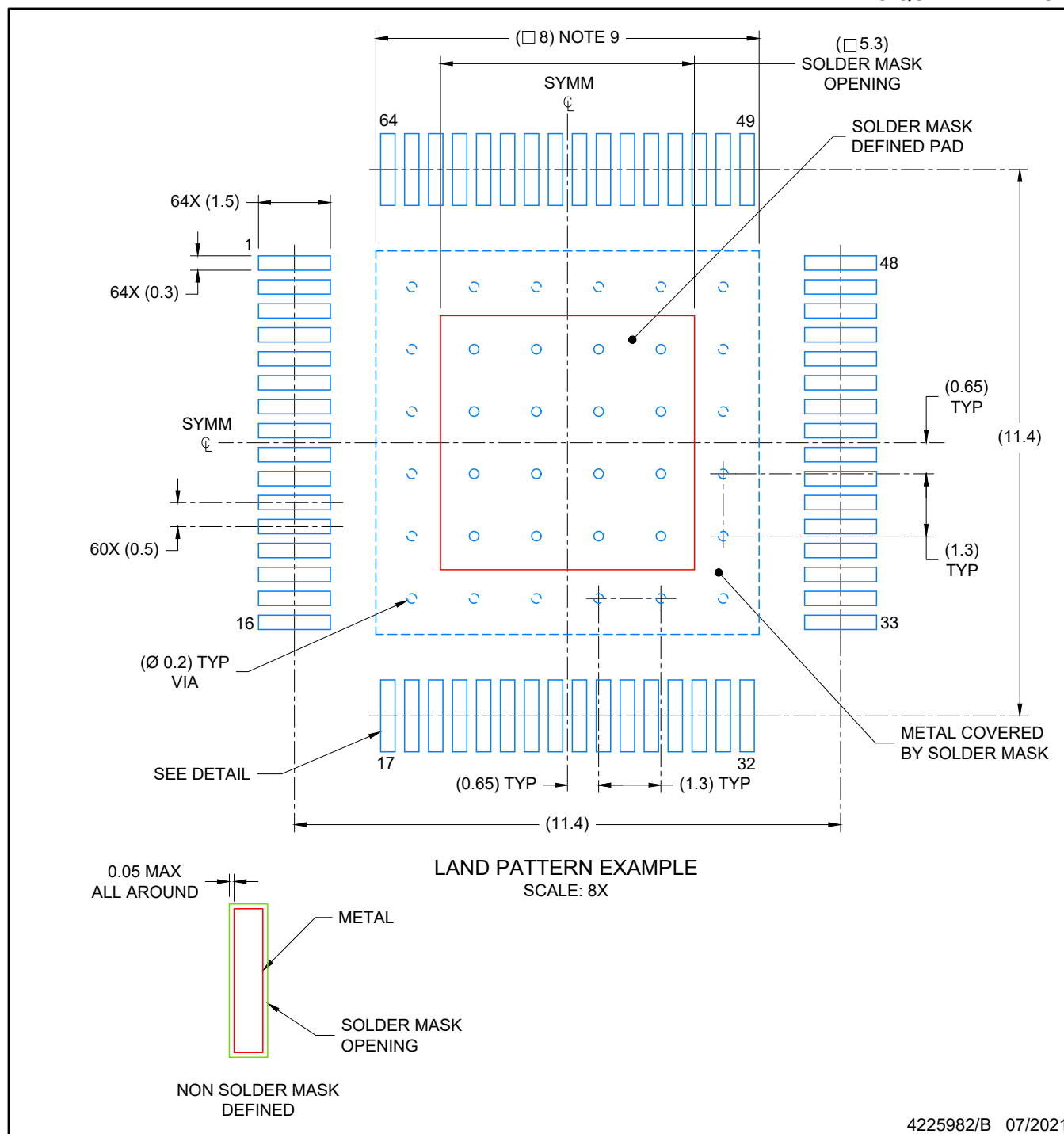


4225982/B 07/2021

NOTES:

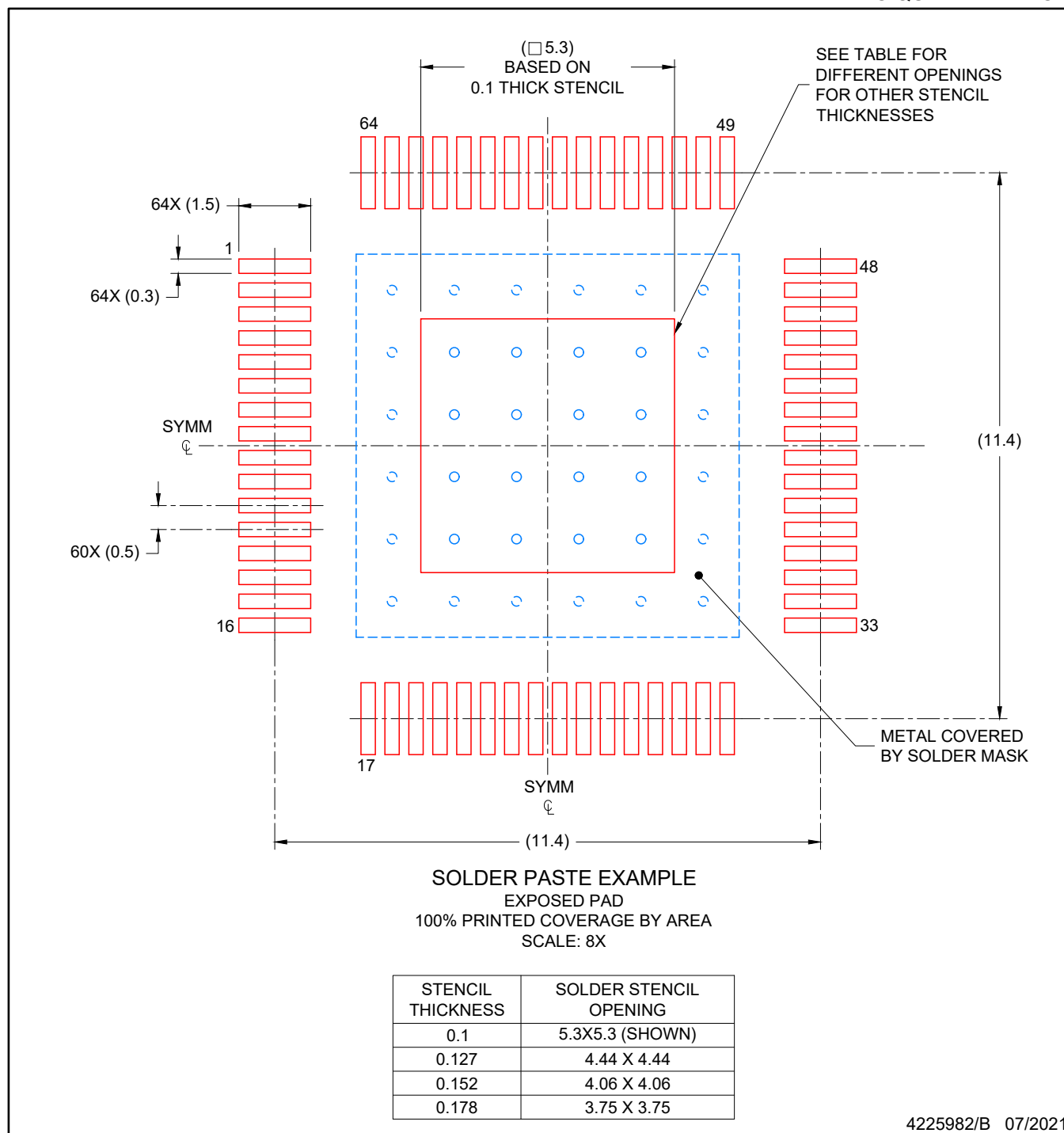
PowerPAD is a trademark of Texas Instruments

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per side.
4. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
5. Strap features may not be present.
6. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
9. This package is designed to be soldered to a thermal pad on the board. Refer to technical brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).



NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated